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(54) **COMPOSITE SUBSTRATE, ELECTRONIC COMPONENT, AND METHOD OF MANUFACTURING COMPOSITE SUBSTRATE AND ELECTRONIC COMPONENT**

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USPC **257/52**; 438/479

(57) **ABSTRACT**

A composite substrate having silicon substrate with excellent crystallinity and a method of manufacturing the composite substrate and an electronic component using the composite substrate are provided. A composite substrate (**1**) is configured to bond a support substrate (**10**) having electrical insulating property, and a silicon substrate (**20**) which is overlaid on the support substrate (**10**). The semiconductor substrate (**20**) of the composite substrate (**1**) includes a plurality of first regions (**20***x*) in which a device function unit functioning as a semiconductor device is formed, and a second region (**20***y*) located between these first regions (**20***x*). In the semiconductor substrate (**20**) of the composite substrate (**1**), an amorphous form (**22**) containing silicon and a metal is present in the second region (**20***y*).

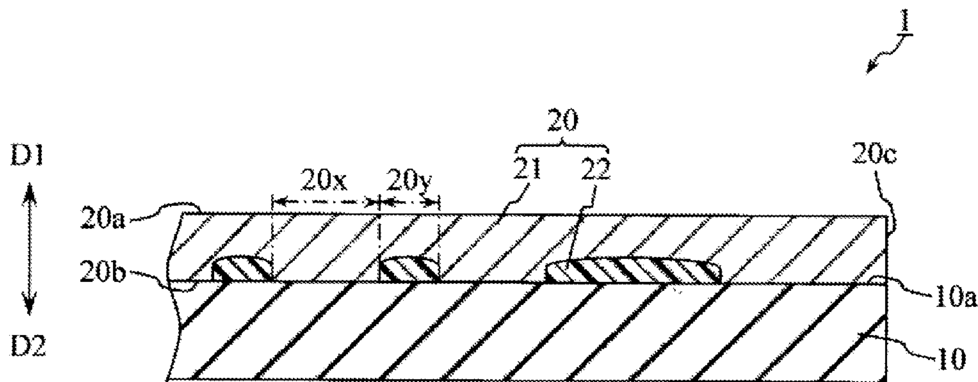
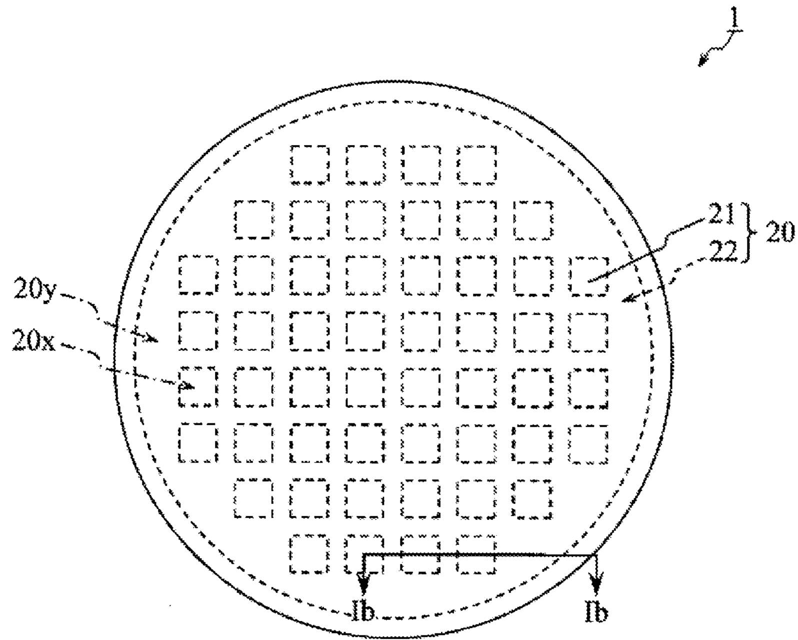
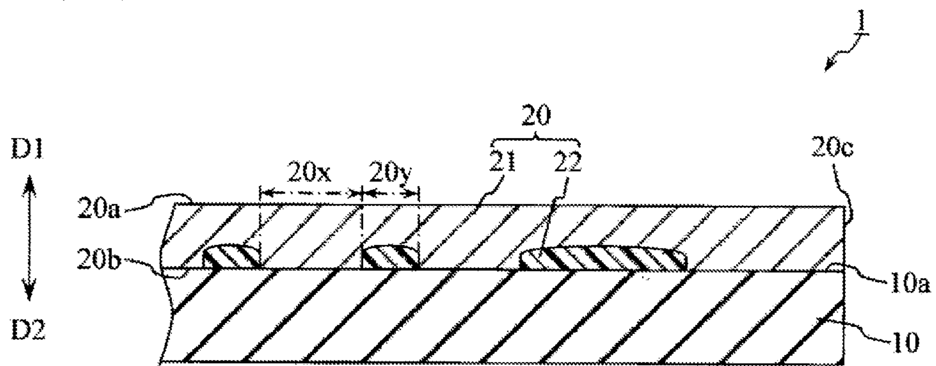


FIG. 1

(a)



(b)



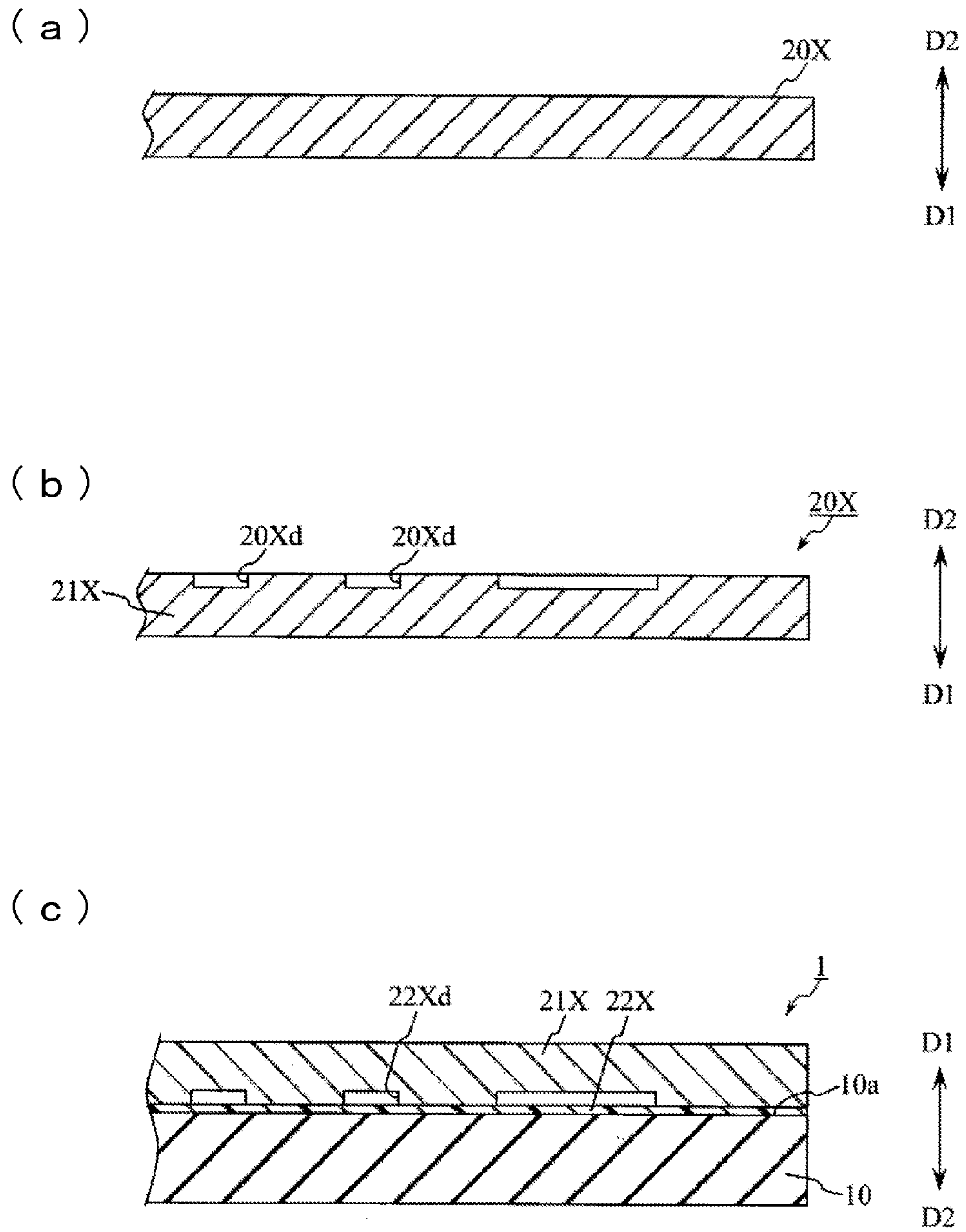


FIG. 2
(a)
20X
D2
D1
(b)
20X
20Xd
20Xd
21X
D2
D1
(c)
1
22Xd
21X
22X
D1
10a
10
D2

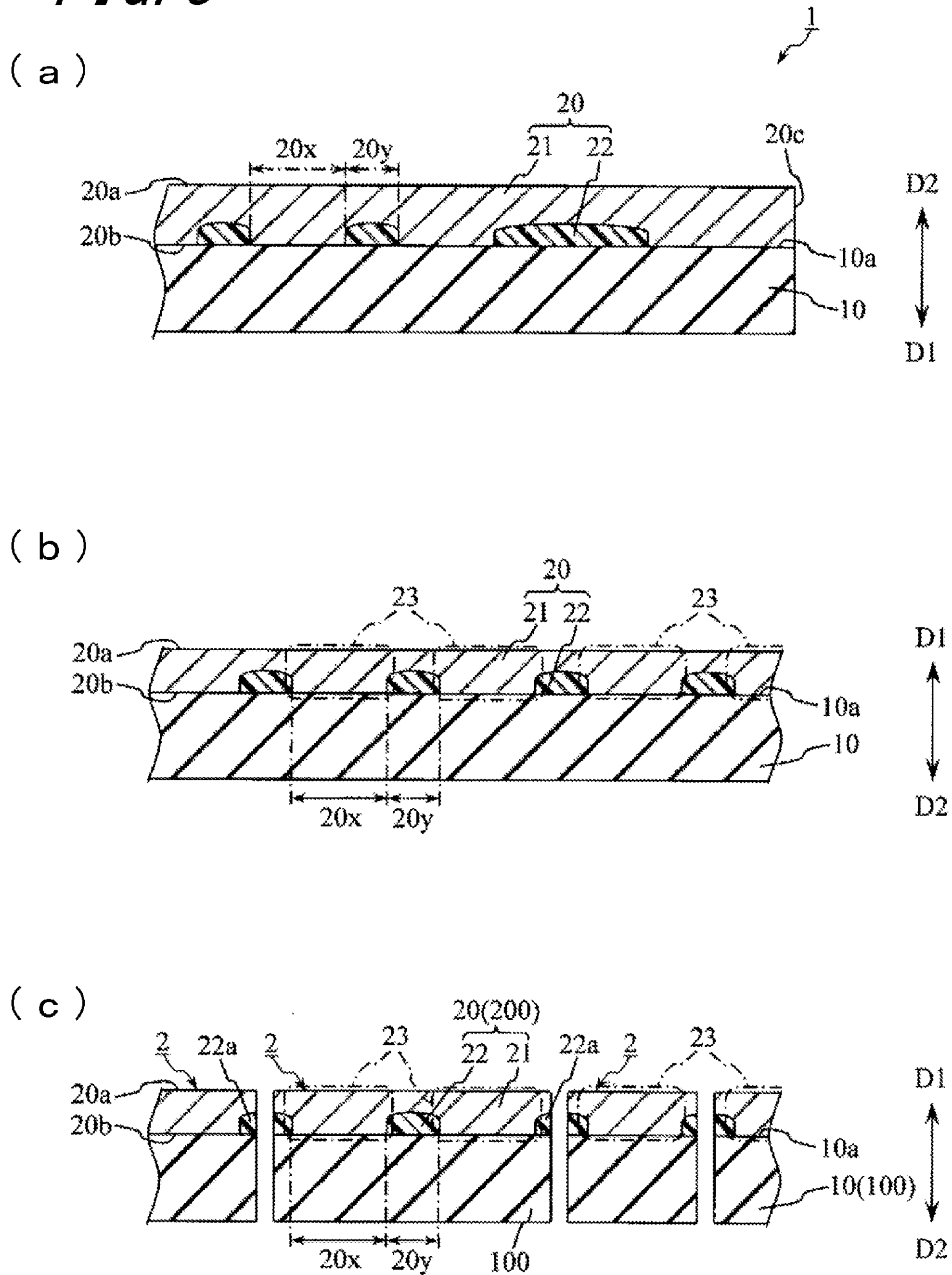
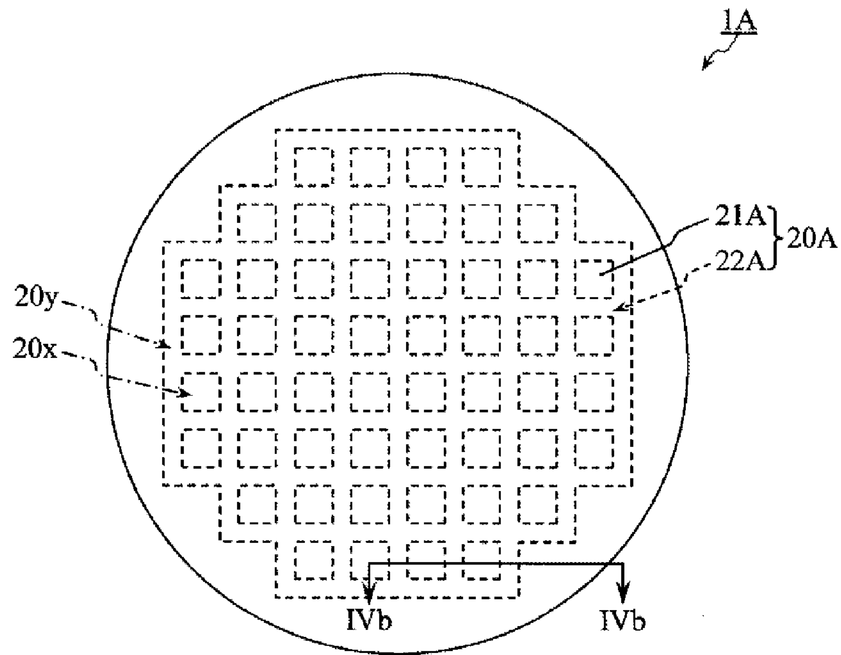


FIG. 3
(a)
1
20
20x
20y
21
22
20c
20a
20b
10a
10
D2
D1
(b)
20
23
21
22
23
20a
20b
10a
10
20x
20y
D1
D2
(c)
20(200)
2
22a
2
23
22
21
22a
2
23
20a
20b
10a
10(100)
20x
20y
100
D1
D2

FIG. 4

(a)



(b)

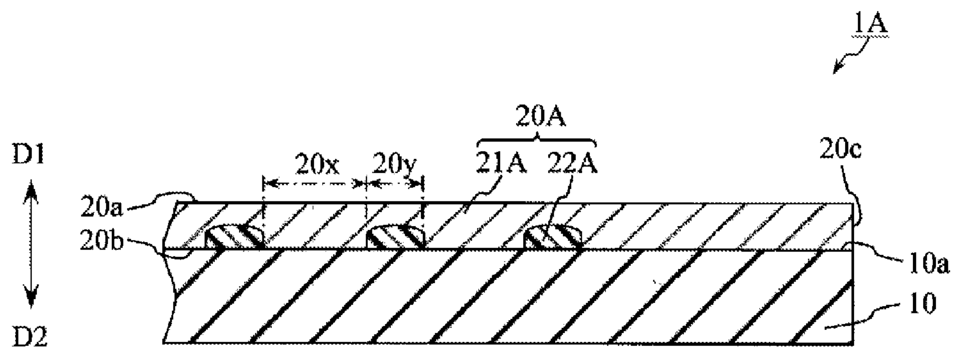


FIG. 5

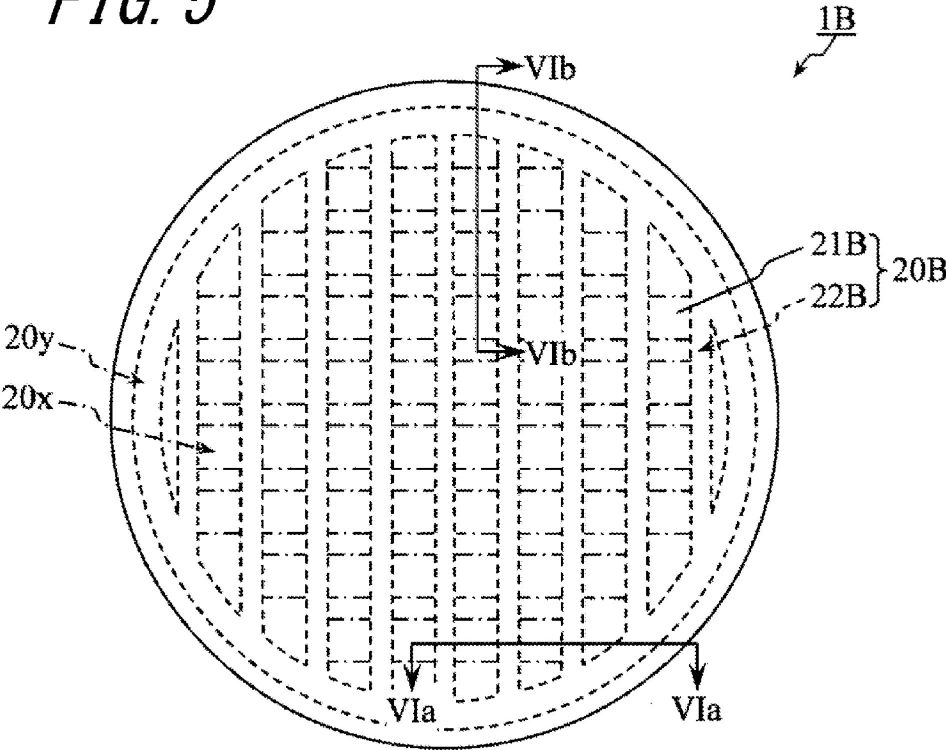
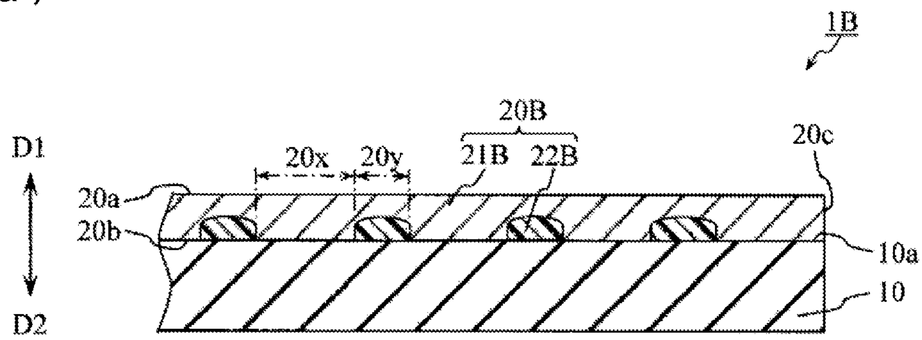


FIG. 6

(a)



(b)

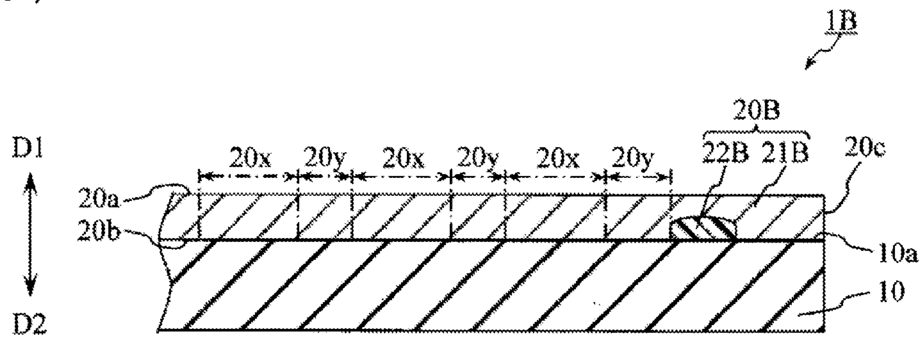


FIG. 7

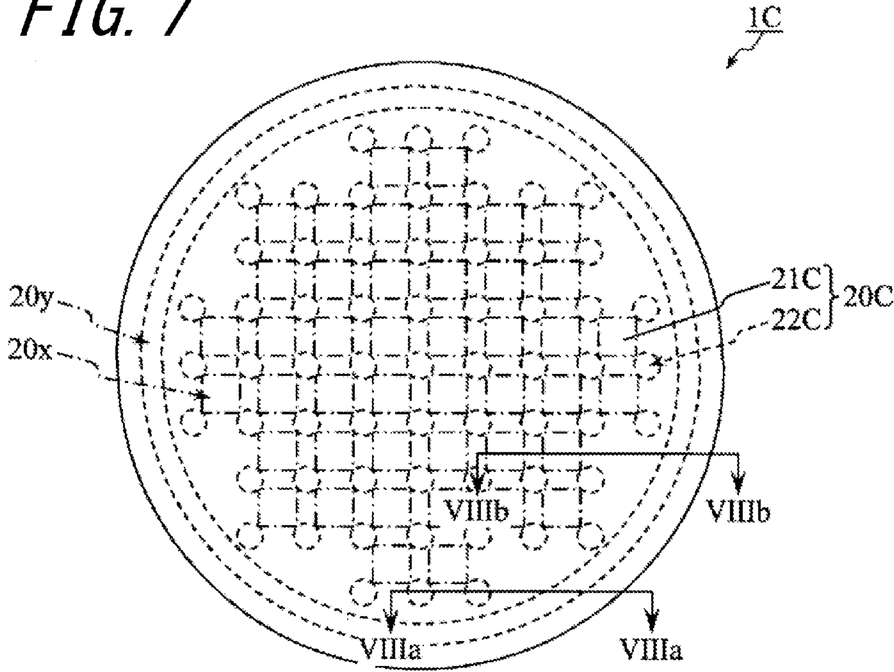
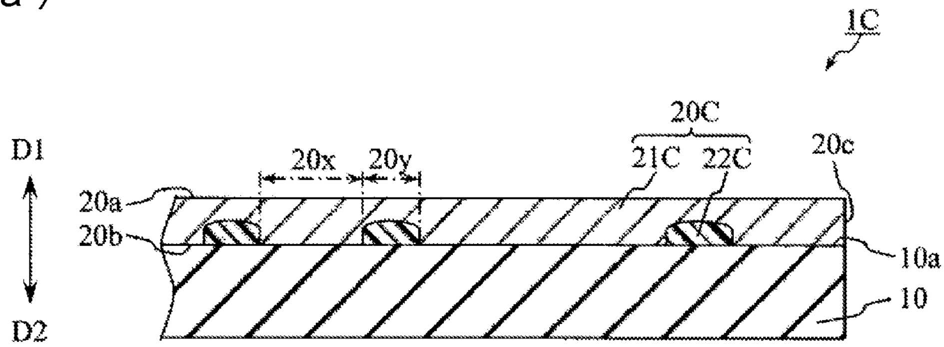
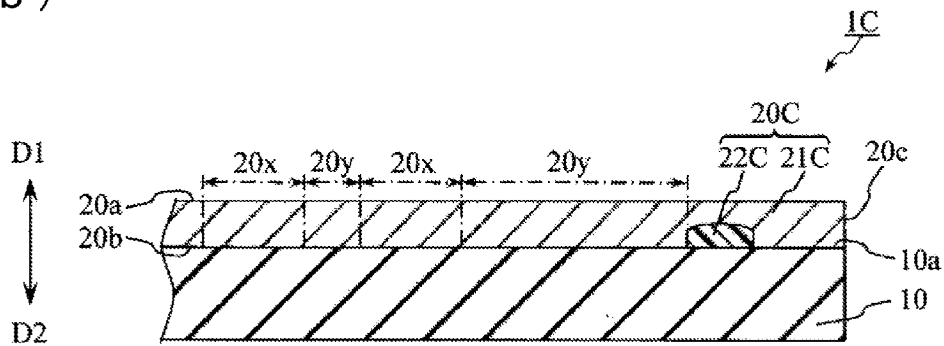


FIG. 8

(a)



(b)



COMPOSITE SUBSTRATE, ELECTRONIC COMPONENT, AND METHOD OF MANUFACTURING COMPOSITE SUBSTRATE AND ELECTRONIC COMPONENT

FIELD OF INVENTION

[0001] The present invention relates to a composite substrate, an electronic component, and a method of manufacturing a composite substrate and an electronic component.

BACKGROUND

[0002] In recent years, in order to achieve performance improvement of a semiconductor device, a technique for decreasing parasitic capacitance has been developed. As a technique for decreasing parasitic capacitance, a silicon-on-sapphire (SOS) structure is known. As a method of forming the SOS structure, for example, a technique disclosed in Japanese Unexamined Patent Publication JP-A 10-12547 (1998) is known.

SUMMARY

[0003] However, in the technique disclosed in JP-A 10-12547 (1998), lattice defect occurs in silicon due to a difference in a lattice structure between silicon and sapphire.

[0004] The invention has been devised in consideration of the above-described situation, and an object of the invention is to provide a composite substrate having silicon substrate with excellent crystallinity and a method of manufacturing the composite substrate and an electronic component using the composite substrate.

[0005] A composite substrate of the invention includes a support substrate having electrical insulating property, and a silicon substrate which is overlaid on the support substrate, wherein the silicon substrate comprises a plurality of first regions and a second region located between the plurality of first regions, and an amorphous form containing silicon and a metal is present in a main surface of the second region which is located at a side of the support substrate.

[0006] A first method of manufacturing a composite substrate of the invention includes bonding a main surface of a silicon substrate onto a support substrate having electrical insulating property through a metal layer, and heating the support substrate and the silicon substrate bonded with each other to form an amorphous form containing silicon and a metal which forms the metal layer on a main surface of the silicon substrate which is located at a side of the support substrate.

[0007] A second method of manufacturing a composite substrate of the invention includes forming a dent portion in a second region between a plurality of first regions on a main surface of a silicon substrate, forming a metal layer on at least one of the main surface of the silicon substrate and a support substrate having electrical insulating property, bonding the main surface of the silicon substrate onto the support substrate through the metal layer, and heating the support substrate and the silicon substrate bonded with each other configured for aggregating the metal layer in the dent portion and forming an amorphous form containing silicon and a metal which forms the metal layer on the main surface of the silicon substrate which is located at a side of the support substrate.

[0008] A method of manufacturing an electronic component of the invention includes forming a device function unit functioning as a semiconductor device in the plurality of the first regions of the composite substrate, and dividing the composite substrate into regions including at least one of the device function unit.

[0009] An electronic component of the invention includes a support chip and a silicon chip located on the support chip, wherein the silicon chip has a first region in which a device portion functioning as a semiconductor device is provided and a second region which is located surrounding the first region, and an amorphous form containing silicon and a metal is present in a main surface of the second region which is located at a side of the support chip.

[0010] A method of manufacturing an electronic component of the invention includes forming a device function unit functioning as a semiconductor device in the plurality of the first regions of the composite substrate, and dividing the composite substrate into regions including at least one of the device function unit.

[0011] According to the invention, it is possible to provide a composite substrate and an electronic component having a silicon substrate with excellent crystallinity, and a method of manufacturing the composite substrate and the electronic component.

BRIEF DESCRIPTION OF THE DRAWINGS

[0012] FIG. **1**(*a*) is a plan view showing the schematic configuration of an embodiment of a composite substrate according to the invention, and FIG. **1**(*b*) is a sectional view taken along the line Ib-Ib of FIG. **1**(*a*);

[0013] FIGS. **2**(*a*) to **2**(*c*) are schematic views showing an embodiment of a process for manufacturing a composite substrate and a semiconductor device according to the invention;

[0014] FIGS. **3**(*a*) to **3**(*c*) are schematic views showing a process subsequent to FIG. **2**;

[0015] FIG. **4**(*a*) is a plan view showing the schematic configuration of a modified example of the composite substrate shown in FIG. **1**, and FIG. **4**(*b*) is a sectional view taken along the line IVb-IVb of FIG. **4**(*a*);

[0016] FIG. **5** is a plan view showing the schematic configuration of a modified example of the composite substrate shown in FIG. **1**;

[0017] FIG. **6**(*a*) is a sectional view taken along the line VIa-VIa of FIG. **5**, and FIG. **6**(*b*) is a sectional view taken along the line VIb-VIb of FIG. **5**;

[0018] FIG. **7** is a plan view showing the schematic configuration of a modified example of the composite substrate shown in FIG. **1**; and

[0019] FIG. **8**(*a*) is a sectional view taken along the line VIIIa-VIIIa of FIG. **7**, and FIG. **8**(*b*) is a sectional view taken along the line VIIIb-VIIIb of FIG. **7**.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

First Embodiment of Composite Substrate

[0020] A composite substrate **1** which is an example of an embodiment of a composite substrate of the invention will be described referring to the drawings. The composite substrate **1** shown in FIG. **1** includes a support substrate **10** and a silicon substrate **20**.

[0021] The support substrate **10** is a support member of the silicon substrate **20** as a semiconductor layer. It should suffice that the support substrate **10** is electrical insulating, and in this

embodiment, the support substrate **10** is formed of aluminum oxide single crystal (hereinafter, referred to as "sapphire"). For the support substrate **10**, a silicon carbide substrate or the like may also be used. The silicon substrate **20** is overlaid on the main surface (hereinafter, referred to as "top surface **10**a") of the support substrate **10** in a D1 direction. In other words, the silicon substrate **20** is supported and bonded directly to the top surface **10**a of the support substrate **10**. The thickness of the support substrate **10** is, for example, in a range of 400 to 800 [μm].

[0022] A device function unit which functions as a semiconductor device is formed in a part of the silicon substrate **20**. In this embodiment, silicon single crystal is used as the silicon substrate **20**. The thickness of the silicon substrate **20** is, for example, in a range of 50 to 300 [nm]. In the silicon substrate **20**, a region where a device function unit is formed is referred to as a first region **20**x, and a region other than the first region **20**x is referred to as a second region **20**y. The first regions **20**x are arranged in a matrix, and part of the second region **20**y located between the first regions **20**x spreads in a lattice shape. The second region **20**y can be used for splitting or cutting when the composite substrate **1** is divided into desired first regions **20**x. The formation and arrangement of the first regions **20**x are not limited to this embodiment, and are appropriately selected. The shape of the second region **20**y is appropriately selected according to the shape and arrangement of the first regions **20**x.

[0023] The silicon substrate **20** includes a main portion **21** and an amorphous form **22**. The main portion **21** is a region which occupies the main part of the silicon substrate **20**, and is formed of silicon single crystal (hereinafter, simply referred to as "silicon"). The main portion **21** is primarily located in the first region **20**x. The amorphous form **22** is a region where the main portion **21** and a metal material are mixed. Examples of the metal material contained in the amorphous form **22** include iron (Fe), nickel (Ni), manganese (Mn), chromium (Cr), and aluminum (Al). The amorphous form **22** is primarily located in the second region **20**y. That is, the amorphous form **22** is formed between the first regions **20**x. The amorphous form **22** faces the main surface (hereinafter, referred to as "lower main surface **20**b") of the silicon substrate **20** in a D2 direction.

[0024] The amorphous form **22** has a bond of an element forming the main portion **21** and a single metal material. When the main portion **21** is Si, and the metal material is Fe, the amorphous form **22** has a Fe—Si bond. The amorphous form **22** is not present on the lower main surface **20**b, and is present only in the second region **20**y. That is, the amorphous form **22** is aggregated, thereby reducing the diffusion depth compared to uniform diffusion. Accordingly, it is possible to suppress the diffusion of the metal material to the silicon substrate **20**.

[0025] The amorphous form **22** can be specified by an electronic energy loss spectroscopy (EELS) or the like.

[0026] It is preferable that the interval between a plurality of first regions **20**x is equal to or greater than 100 [nm]. More preferably, the interval is equal to or greater than 300 [nm]. When a metal is present between a region directly below a portion where a device function unit is formed and the support substrate **10**, device characteristics may be deteriorated. Meanwhile, the interval between the plurality of first regions **20**x is set as described above, it is possible to eliminate a metal which affects a device function unit to be formed in the first region **20**x. The interval between the plurality of first regions **20**x will be described below.

[0027] The amorphous form **22** is formed at an inner portion with reference to different surfaces of the silicon substrate **20** except the lower main surface **20**b of the silicon substrate **20**, that is, a main surface (hereinafter, referred to as "upper main surface **20**a") and a lateral surface **20**c of the silicon substrate **20** in the D1 and D2 directions. In other words, the main portion **21** faces the upper main surface **20**a and the lateral surface **20**c of the silicon substrate **20**. That is, the exposed region of the silicon substrate **20** has the same composition. For this reason, in the silicon substrate **20**, an effective process can be selected from various processes relating to silicon and appropriately used.

[0028] The amorphous form **22** is arranged surrounding the first region **20**x. The adhesion strength of sapphire and the amorphous form **22** is greater than the adhesion strength of sapphire and silicon. The amorphous form **22** faces the lower main surface **20**b of the silicon substrate **20**, thereby increasing the adhesion strength of bonding of the support substrate **10** and the silicon substrate **20**. In the composite substrate **1**, even after the composite substrate **1** is divided as a semiconductor device, it is possible to satisfactorily adhere the support substrate **10** and the silicon substrate **20**. The configuration of this embodiment may be restated as the individual first region **20**x being divided by the amorphous form **22**.

[0029] It is preferable that the roughness of the bonded surfaces of the support substrate **10** and the silicon substrate **20** is small, and for example, a mean roughness Ra (arithmetic mean roughness) is smaller than 10 [nm]. The mean roughness Ra decreases, thereby reducing pressure to be applied when bonding. In particular, Ra is equal to or smaller than 1 [nm], thereby performing bonding with very small pressure.

Method of Manufacturing Composite Substrate and Semiconductor Device

[0030] An example of an embodiment of a method of manufacturing a composite substrate and a semiconductor device of the invention will be described referring to FIGS. **2** to **4**.

[0031] First, as shown in FIG. **2**(a), a semiconductor substrate **20**X which becomes the silicon substrate **20** is prepared. In this embodiment, a silicon substrate is adopted as the semiconductor substrate **20**X.

[0032] Next, as shown in FIG. **2**(b), in the main surface of the semiconductor substrate **20**X, dent portions **20**Xd are formed in one main surface which becomes the lower main surface **20**b of the silicon substrate **20**. The dent portion **20**Xd is formed in a region which becomes the second region **20**y. As a method of forming the dent portion **20**Xd, for example, a method in which silicon is partially oxidized using a photomask to selectively remove silicon oxide, or a desired portion is etched using a mask is used. As the oxidization, for example, various methods, such as thermal oxidization, solution oxidization, and the like, are adopted. As etching, a chemical method or a physical method, such as an ion beam, is used. As the mask, for example, a metal mask, a photomask, and the like are known and appropriately selected according to an etching method.

[0033] It should suffice that the depth of the dent portion **20**Xd is, for example, about 10 [nm]. It is preferable that the depth of the dent portion **20**Xd is smaller than the difference

between the thickness in the first region **20***x* and the thickness of a device function unit **23** described below.

[0034] Next, as shown in FIG. **2**(*c*), the support substrate **10** and the semiconductor substrate **20**X are bonded together through a metal layer **22**X. As the bonding method, a method in which the surfaces to be bonded are activated to perform bonding, and a method in which an electrostatic force is used to perform bonding are used. As the method of activating the surfaces, for example, a method in which an ion beam is irradiated in vacuum to etch and activate the surfaces, or the like is used. It is preferable that the bonding is performed at normal temperature. During the bonding, a method in which a resin-based adhesive is not used is adopted, and bonding is performed by solid state bonding using an atomic force or the like.

[0035] As the metal material which forms the metal layer **22**X, for example, Fe, Cr, Ni, Mn, Al, and Cu may be used alone or in combination. The metal material is supplied to the activated surfaces by activating a metal supply source in a bonding apparatus simultaneously with irradiation of an ion beam during bonding. The thickness of the metal layer **22**X is not particularly limited, and is, for example, equal to or smaller than 5 [nm]. The metal layer **22**X may be in a state where metal elements (particles) are stuck, that is, in a network shape. The metal layer **22**X is present on the bonding interface when the surfaces are activated and bonded, and in general SOI, since thermal compression bonding is performed through an oxide, it is not even necessary to provide the metal layer.

[0036] Next, the semiconductor substrate **20**X is thinned so as to have a desired thickness. As the thinning method, various methods, such as abrasive-grain polishing, chemical etching, and ion beam etching, can be adopted, and multiple methods may be combined.

[0037] The surface of the semiconductor substrate **20**X may be smoothened by precise etching along with the thinning. As etching means using precise etching, for example, dry etching is used. The dry etching includes dry etching by chemical reaction and dry etching by physical collision. As the dry etching using chemical reaction, dry etching using reactive gas, ions and ion beams, or radicals is used. As etching gas which is used for reactive ions, sulfur hexafluoride (SF_6), carbon tetrafluoride (CF_4), or the like is used. As dry etching by physical collision, dry etching using ion beams is used. The dry etching using ion beams includes a method using a gas cluster ion beam (GCIB). The semiconductor substrate **20**X is scanned with a movable stage while etching a narrow region using the etching means, thereby satisfactorily performing precise etching even on a large-area material substrate.

[0038] Next, the support substrate **10** and the semiconductor substrate **20**X bonded with each other are heated for aggregating the metal layer **22**X in the dent portion **20**X*d*. The aggregated metal layer **22**X is mixed with silicon of the semiconductor substrate **20**X, and thus the amorphous form **22** is formed. Since silicon of the semiconductor substrate **20**X is used in forming the amorphous form **22**, the shape of the dent portion **20**X*d* of the semiconductor substrate **20**X changes. That is, a corner portion or a smoothed portion constituting the dent portion **20**X*d* having a rectangular sectional shape is eliminated. The dent portion **20**X*d* has a shape according to the shape of the amorphous form **22** as an aggregate.

[0039] The temperature in the heating condition is equal to or higher than the melting point of each metal, and more preferably, is equal to or higher than an eutectic temperature of the element forming the semiconductor substrate **20**X and the metal material. For example, in this embodiment, a state equal to or higher than 500° C. is maintained for 30 minutes or more, thereby aggregating the metal layer in the dent portion **20**X*d*. An atmosphere during heating is not particularly limited, and any one of air, oxygen, nitrogen, inert gas, reductive gas, and the like may be selected.

[0040] As in this embodiment, when the support substrate **10** and the semiconductor substrate **20**X are bonded together in vacuum by activating and bonding the surfaces, it is inferred that a cavity is partially generated in the bonding interface. In particular, in this example, since the dent portion **20**X*d* is provided, in normal-temperature bonding by activating the bonded surfaces, a cavity is generated in the bonding interface. It is considered that, through heating after bonding, the metal is molten, moved so as to bury the cavity, and aggregated at a predetermined place. That is, in this embodiment, the dent portion **20**X*d* is provided at an intended position, thereby controlling the aggregate position of the metal.

[0041] As described above, it is possible to obtain the composite substrate **1** in which the silicon substrate **20** is bonded onto the support substrate **10** having electrical insulation. The silicon substrate **20** of the composite substrate **1** includes a plurality of first regions **20***x* where a device function unit functioning as a semiconductor device is formed, and the second region **20***y* which is located between the first regions **20***x*. In the semiconductor substrate **20** of the composite substrate **1**, the amorphous form **22** of silicon and metal is provided in the second region **20***y*.

[0042] Next, as shown in FIG. **3**(*b*), the device function unit **23** is formed from the upper main surface **20***a* side of the obtained composite substrate **1**. The device function unit **23** is formed in an arbitrary first region **20***x*. As the device function unit **23**, various semiconductor device structures are used. In FIG. **3**(*a*) and FIGS. **3**(*b*) and **3**(*c*), different locations are shown.

[0043] Next, as shown in FIG. **3**(*c*), the composite substrate **1** in which the device function unit **23** is formed is divided, and thus the electronic component **2** is manufactured. When dividing the composite substrate **1** into the electronic component **2**, at least one of the device function unit **23** is included in one electronic component **2**. In other words, the plurality of first regions **20***x*, and consequently, a plurality of device function units **23** may be included in one electronic component **2**.

[0044] At least one of the amorphous form **22** and the amorphous form **22***a* obtained by dividing the amorphous form **22** is included in one electronic component **2**. The amorphous form **22** or the divided amorphous form **22***a* is included in one electronic component **2**, thereby satisfactory adhering a support chip **100** and a silicon chip **200** when using as the electronic component **2**.

[0045] In this way, it is possible to manufacture the electronic component **2** having the device function unit **23**.

[0046] The invention is not limited to the foregoing embodiment, and it should be noted that various variations may be made without departing from the scope of the invention.

[0047] For example, although in the silicon substrate **20**, the amorphous form **22** is formed from the edge of the first region **20***x* to the edge of the main portion **21**, the amorphous form **22** is not limited to this shape. For example, as a silicon

substrate **20**A shown in FIG. **4**, an amorphous form **22**A may surround the edge of the first region **20***x*.

[0048] In the silicon substrate **20**, although the amorphous form **22** surrounds the first region **20***x* in a lattice shape, the amorphous form **22** is not limited to this shape, for example, as a silicon substrate **20**B shown in FIG. **5**, a pair of amorphous forms **22**B which extend along the first region **20***x* may be provided. As a silicon substrate **20**C shown in FIG. **6**, amorphous forms **22**C may be provided at four corners of the first region **20***x*.

[0049] In the above-described manufacturing method, although the metal layer **22**X is aggregated to form the amorphous form **22**, a part of the metal layer **22**X may form the amorphous form **22**, and the other part may be left as the metal layer **22**X. A part which is left as the metal layer **22**X may not have uniform concentration, and the concentration distribution of the metal may be generated.

Modified Example of Method of Manufacturing Composite Substrate

[0050] In the above-described manufacturing method, as shown in FIG. **2**(*b*), although the dent portion **20**X*d* is formed in the silicon substrate **20**, and the metal is aggregated in the dent portion **20**X*d*, the dent portion **20**X*d* may not be provided. In this case, the thickness (corresponding to the supply metal amount) of the metal layer **22**X to be formed in FIG. **2**(*c*) is adjusted, thereby aggregating the metal layer **22**X at a given interval according to the supply metal amount. Similarly, the size of the amorphous form **22** depends on the supply metal amount.

[0051] For example, when the metal supply amount is 1×10^{16} [atoms/cm^3], the interval of the amorphous form **22** can be about 100 [nm].

[0052] From the relationship between the metal supply amount and the interval of the amorphous form **22**, it is preferable that the interval of the amorphous form **22** is smaller than 100 [nm], because in this case it is possible to suppress the adverse effect of the size of the amorphous form **22** on the operation characteristics as the electronic component **2**. It is preferable that the interval of the amorphous form **22** is equal to or greater than 300 [nm], because in this case it is possible to further reduce the size of the amorphous form **22** and to suppress the adverse effect on the operation characteristics as the electronic component **2**. Specifically, it is preferable that the size of the amorphous form **22** in the thickness direction is smaller than the size obtained by subtracting the thickness required to form the semiconductor device function unit **23** from the thickness of the thickness silicon substrate **20**.

REFERENCE SIGNS LIST

[0053] **1**, **1**A to **1**C: Composite substrate
[0054] **2**: Electronic component
[0055] **10**: Support substrate
[0056] **10***a*: Top surface
[0057] **20**, **20**A to **20**C: Semiconductor layer
[0058] **20***a*: Upper main surface
[0059] **20***b*: Lower main surface
[0060] **20***c*: Lateral surface
[0061] **20***x*: First region
[0062] **20***y*: Second region
[0063] **20**X: Semiconductor substrate
[0064] **20**X*d*: Dent portion
[0065] **21**, **21**A to **21**C: Main portion
[0066] **22**, **22**A to **22**C: Amorphous form
[0067] **22***a*: Divided amorphous form
[0068] **22**X: Metal layer
[0069] **23**: Device function unit

1. A composite substrate, comprising:
a support substrate having electrical insulating property; and
a silicon substrate which is overlaid on the support substrate, wherein
the silicon substrate comprises a plurality of first regions and a second region located between the plurality of first regions, and
an amorphous form containing silicon and a metal is present in a main surface of the second region which is located at a side of the support substrate.

2. The composite substrate according to claim **1**,
wherein the support substrate is single crystal predominantly composed of aluminum oxide.

3. The composite substrate according to claim **1**,
wherein the amorphous form surrounds the plurality of first regions.

4. The composite substrate according to claim **1**,
wherein the amorphous form is located at an inner portion with reference to surfaces of the silicon substrate except the main surface of the silicon substrate located at the side of the support substrate.

5. The composite substrate according to claim **1**,
wherein the amorphous form is located at an inner portion with reference to a lateral surface of the silicon substrate.

6. The composite substrate according to claim **1**,
wherein the plurality of first regions are arranged at an interval equal to or greater than 100 nm.

7. The composite substrate according to claim **1**,
wherein the plurality of first regions are arranged at an interval equal to or greater than 300 nm.

8. A method of manufacturing a composite substrate, comprising:
bonding a main surface of a silicon substrate onto a support substrate having electrical insulating property through a metal layer; and
heating the support substrate and the silicon substrate bonded with each other to form an amorphous form containing silicon and a metal which forms the metal layer on a main surface of the silicon substrate which is located at a side of the support substrate.

9. A method of manufacturing a composite substrate, comprising:
forming a dent portion in a second region between a plurality of first regions on a main surface of a silicon substrate;
forming a metal layer on at least one of the main surface of the silicon substrate and a support substrate having electrical insulating property;
bonding the main surface of the silicon substrate onto the support substrate through the metal layer; and
heating the support substrate and the silicon substrate bonded with each other configured for aggregating the metal layer in the dent portion and forming an amorphous form containing silicon and a metal which forms the metal layer on the main surface of the silicon substrate which is located at a side of the support substrate.

10. A method of manufacturing an electronic component, comprising:

forming a device function unit functioning as a semiconductor device in the plurality of the first regions of the composite substrate according to claim **1**; and

dividing the composite substrate into regions including at least one of the device function unit.

11. The method of manufacturing an electronic component according to claim **10**,

wherein, in dividing the composite substrate, the composite substrate is divided such that the second region is exposed in a divided surface formed by dividing the composite substrate.

12. An electronic component, comprising:

a support chip having electrical insulating property; and

a silicon chip located on the support chip, wherein

the silicon chip has a first region in which a device portion functioning as a semiconductor device is provided and a second region which is located surrounding the first region, and

an amorphous form containing silicon and a metal is present in a main surface of the second region which is locate at a side of the support chip.

13. The electronic component according to claim **12**,

wherein the second region is located on an entire outer lateral surface of the silicon chip.

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